



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 5, 2008

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION AND
ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230 Group: 1792

Confirmation No.: 7180

Filed: April 14, 2006 Examiner: Bareford

International Application No.: PCT/JP2004/014049

International Filing Date: September 17, 2004

Atty. Docket No.: 4700.P0328US

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

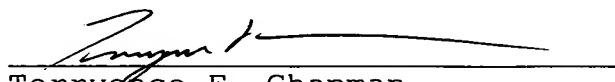
Sir:

In response to the Office Action dated May 8, 2008,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
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addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on August 5, 2008.


Terryence F. Chapman